

JMSH0401MGQ

Product Summary

Parameters	Value	Unit
V_{DSS}	40	V
$V_{GS(th_Typ)}$	2.7	V
$I_D(@V_{GS}=10V)$	223	A
$R_{DS(ON)_Typ}(@V_{GS}=10V)$	1.4	m

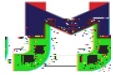
Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMSH0401MGQ-13	SH0401MQ	1	Tape&Reel	PDFN5x6-8L	5000	50000

Absolute Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-to-Source Voltage	40	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	223
		$T_C = 100^\circ\text{C}$	158
I_{DM}	Pulsed Drain Current ⁽¹⁾	Refer to Fig.4	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	459	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	157
		$T_C = 100^\circ\text{C}$	78
T_J STG			$^\circ\text{C}$

Symbol	Parameter	Max	Unit
R	Thermal Resistance, Junction to Ambient ⁽³⁾	42	$^\circ\text{C/W}$
R	Thermal Resistance, Junction to Case	1.0	$^\circ\text{C/W}$

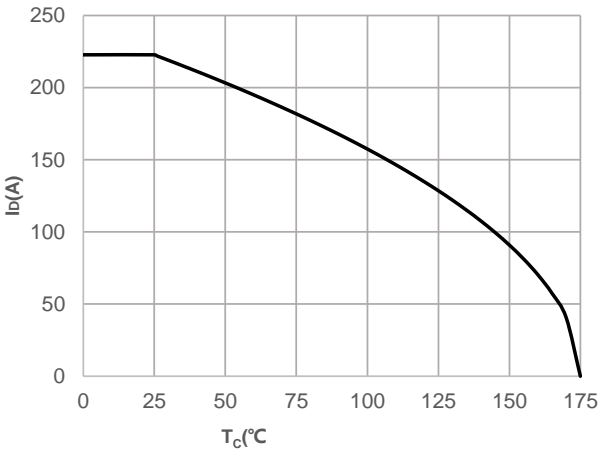
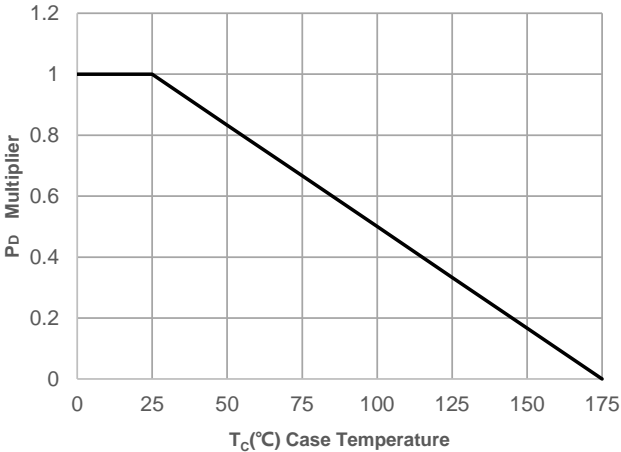
**Electrical Characteristics** ($T_J = 25^\circ\text{C}$ unless otherwise specified)

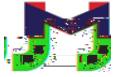
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\text{ A}, V_{GS} = 0\text{V}$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 32\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ A}$	1.9	2.7	3.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10\text{V}, I_D = 20\text{A}$	-	1.4	1.7	m
Dynamic Characteristics						
R_g	Gate Resistance	$f = 1\text{MHz}$	-	0.9	-	
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 20\text{V}, f = 1\text{MHz}$	2589	3625	4893	pF
C_{oss}	Output Capacitance		1413	1979	2671	pF
C_{riss}	Reverse Transfer Capacitance		113	158	213	pF
Q_g	Total Gate Charge	$V_{GS} = 0\text{ to }10\text{V}$ $V_{DS} = 20\text{V}, I_D = 20\text{A}$	42	59	80	nC
Q_{GS}	Gate Source Charge		11	15	21	nC
Q_{gd}	Gate Drain("Miller") Charge		12	16	22	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}, V_{DD} = 20\text{V}$ $I_D = 20\text{A}, R_{GEN} = 3$	-	16	-	ns
t_r	Turn-On Rise Time		-	29	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	35	-	ns
t_f	Turn-Off Fall Time		-	13	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	223	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	891	A
V_{SD}	Body Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 20\text{A}$	-		1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F = 20\text{A}, di/dt = 100\text{A/us}$	37	52	70	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	66	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 20\text{V}$, $V_{GS} = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 3\text{mH}$, $I_{AS} = 17.5\text{A}$, $V_{DD} = 0\text{V}$ during time in avalanche.
 3. $R_{\theta JC}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
 4. Pulse Test: Pulse Width 0.5%.

Typical Performance Characteristics

Figure 1: Power De-rating





Typical Performance Characteristics

Figure 5: Output Characteristics

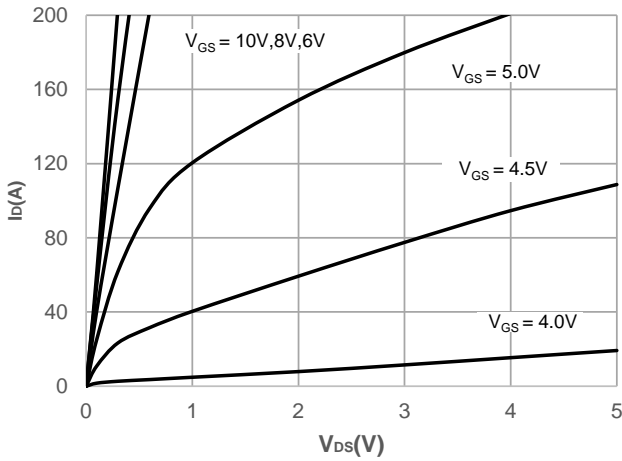


Figure 6: Typical Transfer Characteristics

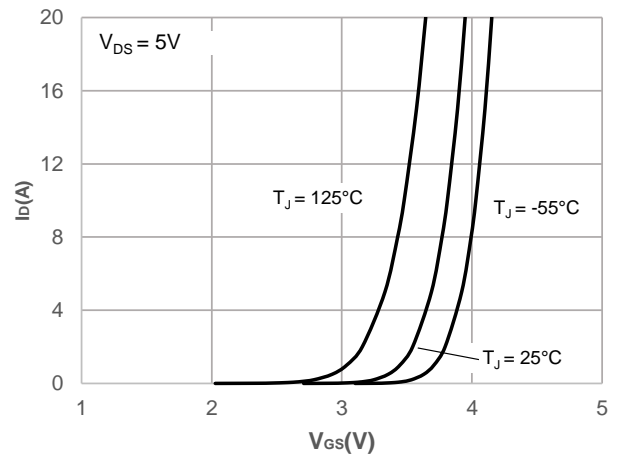


Figure 7: On-resistance vs. Drain Current

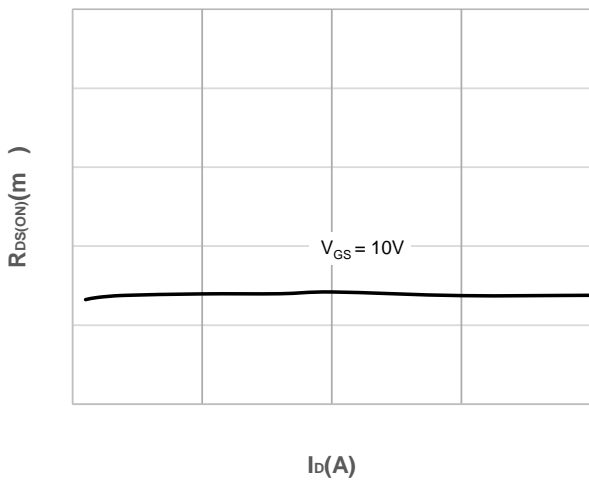


Figure 8: Body Diode Characteristics

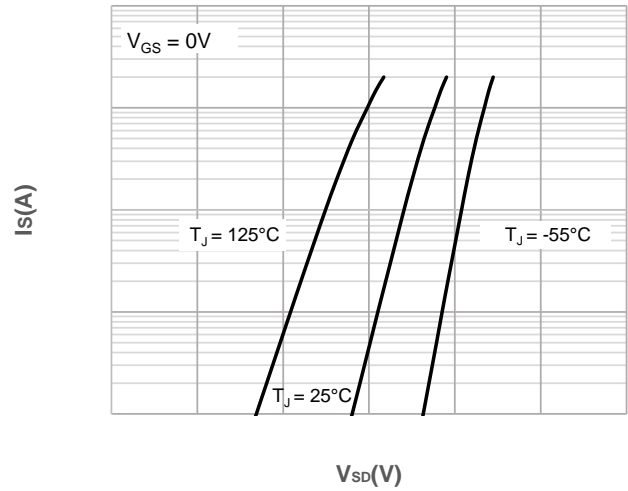


Figure 9: Gate Charge Characteristics

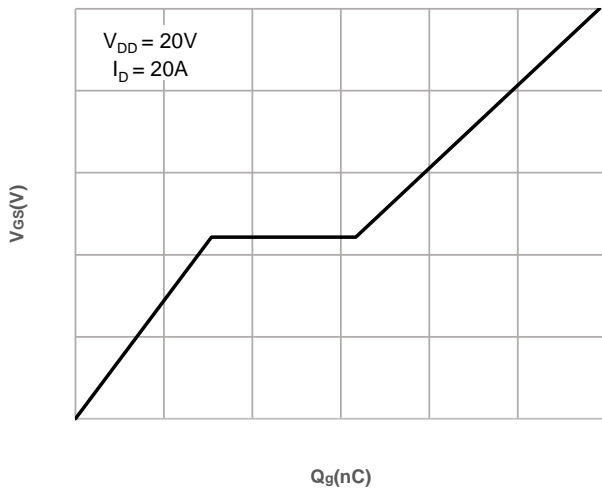
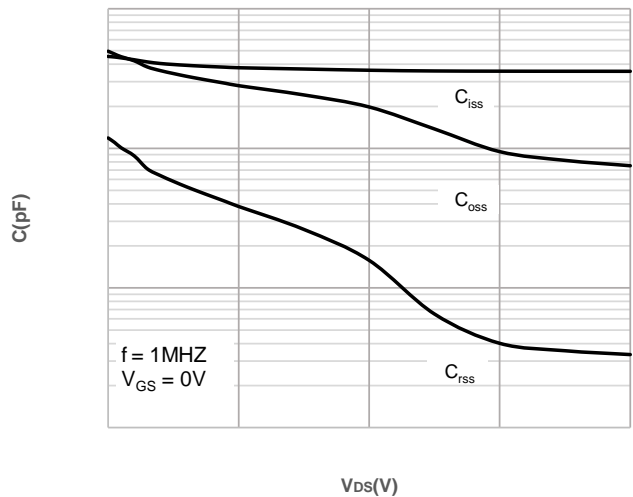


Figure 10: Capacitance Characteristics



Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

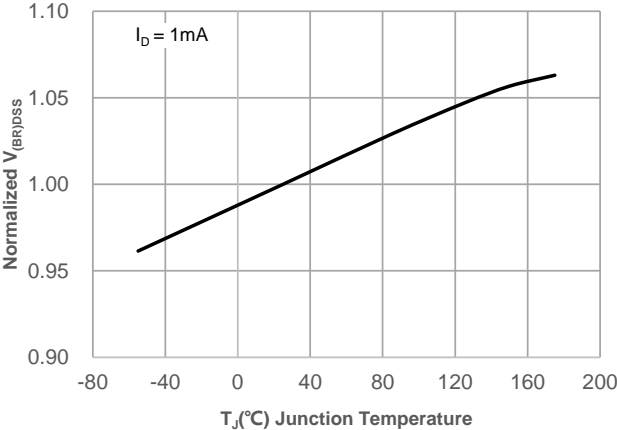


Figure 12: Normalized on Resistance vs. Junction Temperature

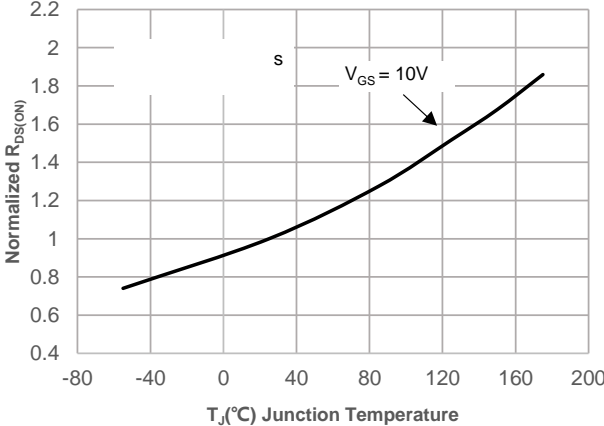
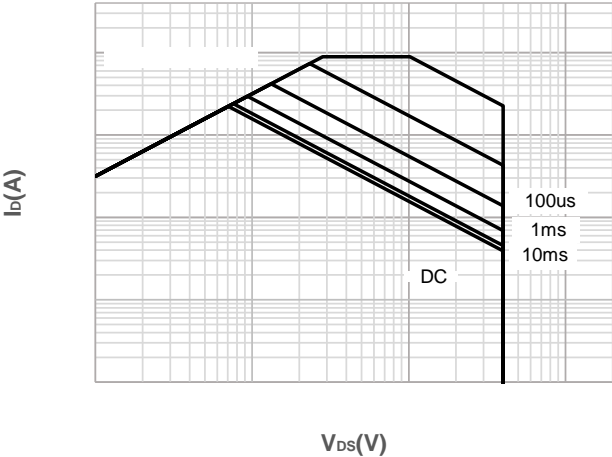
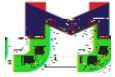


Figure 15: Maximum Safe Operating Area

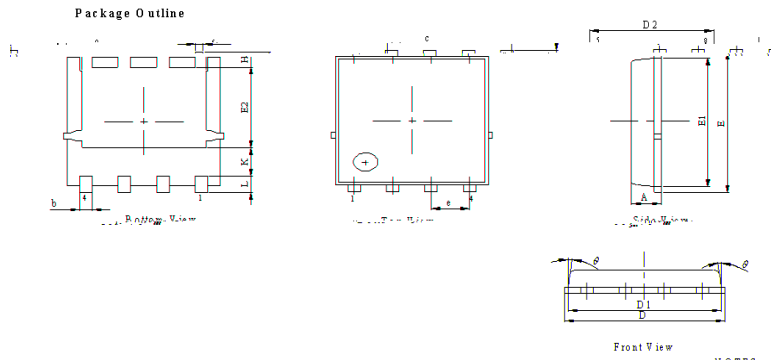


Test Circuit

Figure 1: Gate



Package Mechanical Data(PDFN5X6-8L)

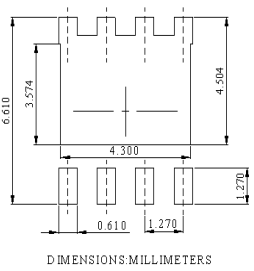


Dimension and tolerance per ASME Y14.5M, 1994.
 All dimensions in millimeter (angle in degree).

NOTES:
 1. Dim
 2. All
 3. D1
 4. D2

MILLIMETER			
MIN.	NOM.	MAX.	
0.2	0	0.15	A
0.21	0.1	0.21	B
1.15	1.15	1.1	C
4.95	5.05	5.15	D1
4	4.1	4.2	D2
6.05	6.15	6.25	E
5.5	5.6	5.7	E1
0.25	0.25	0.25	H
0.25	0.25	0.25	I
0.25	0.25	0.25	L
0.25	0.25	0.25	S

Footprint



Recommended Soldering

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